

**ABSTRACT****U-SHAPE TAPE FOR BOC FBGA PACKAGE TO IMPROVE  
MODLABILITY**

An FBGA packaged device including a die adhered to a substrate with a small gap being formed between the die and substrate. An opening is formed through the substrate adjacent the center portion of the die. An encapsulating mold is formed around the die extending into the gap and also filling the channel. At least one barrier is disposed in the gap between the substrate and the die adjacent the channel to control the flow path of the encapsulating material as the mold is formed in the package.

**Figure 1**